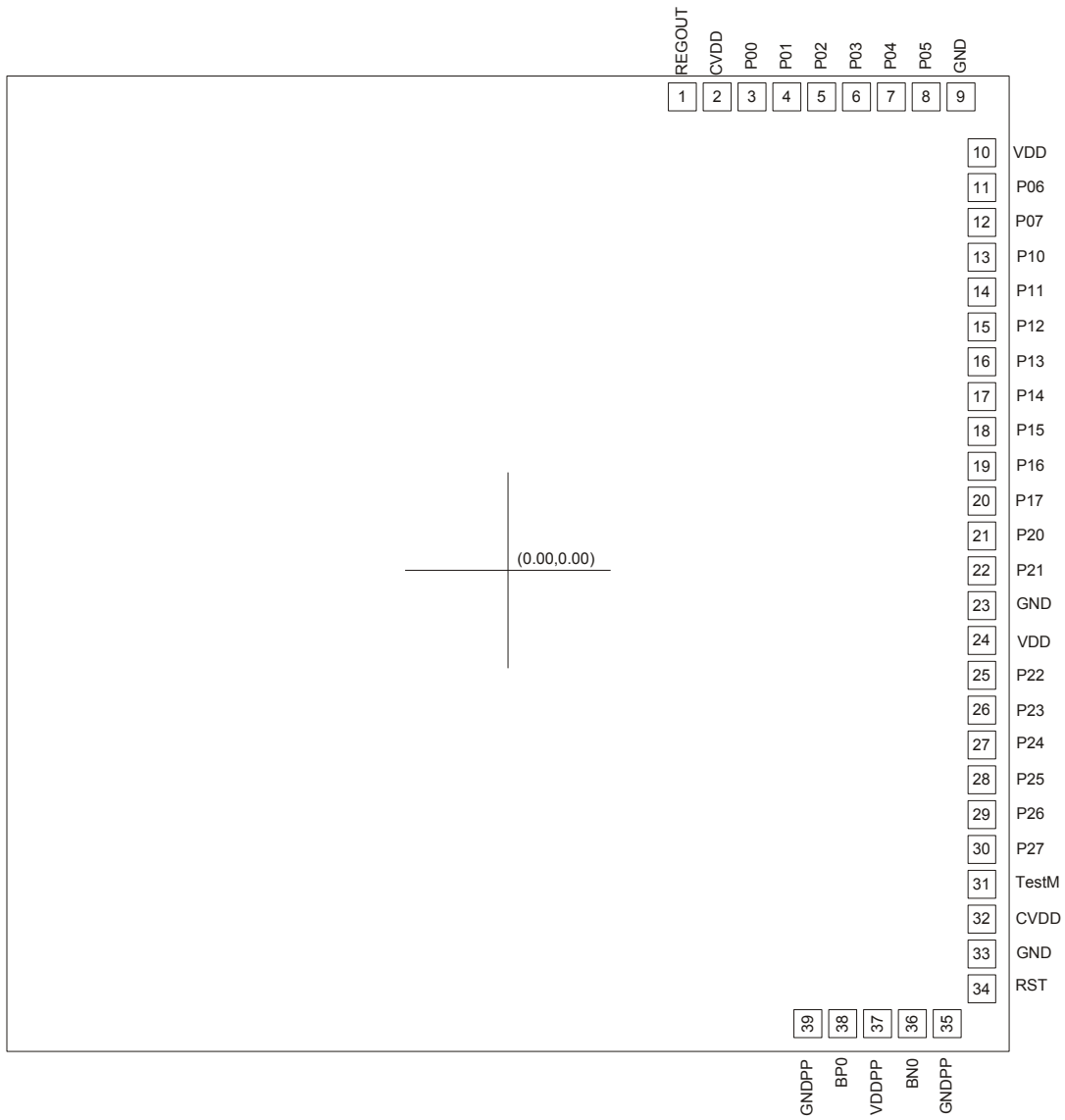




PROJECT: SNC82120B

NO	PAD NAME	X (um)	Y (um)	NO	PAD NAME	X (um)	Y (um)
1	REGOUT	103.39	1306.79	25	P22	1094.41	49.45
2	CVDD	210.58	1306.79	26	P23	1094.41	-30.55
3	P00	312.27	1306.79	27	P24	1094.41	-110.55
4	P01	392.27	1306.79	28	P25	1094.41	-190.55
5	P02	472.27	1306.79	29	P26	1094.41	-270.55
6	P03	552.27	1306.79	30	P27	1094.41	-350.55
7	P04	632.27	1306.79	31	TestM	1094.41	-430.55
8	P05	712.27	1306.79	32	CVDD	1094.41	-510.55
9	GND	792.27	1306.79	33	GND	1094.41	-590.55
10	VDD	1094.41	1249.45	34	RST	1094.41	-670.55
11	P06	1094.41	1169.45	35	GNDPP	1040.71	-1298.00
12	P07	1094.41	1089.45	36	BN0	930.71	-1298.00
13	P10	1094.41	1009.45	37	VDDPP	770.01	-1298.00
14	P11	1094.41	929.45	38	BP0	609.31	-1298.00
15	P12	1094.41	849.45	39	GNDPP	499.31	-1298.00
16	P13	1094.41	769.45				
17	P14	1094.41	689.45				
18	P15	1094.41	609.45				
19	P16	1094.41	529.45				
20	P17	1094.41	449.45				
21	P20	1094.41	369.45				
22	P21	1094.41	289.45				
23	GND	1094.41	209.45				
24	VDD	1094.41	129.45				



SNC82120B

CHIP SIZE: X=2275.815um, Y=2700um

Note: The substrate MUST be connected to GND in PCB layout.